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SAKATA YOSHIKAZU****(54) RADIATION SENSITIVE RESIN COMPOSITION**

(57) Abstract:

PURPOSE: To obtain a radiation sensitive resin compsn. having high sensitivity to radiation and excellent resistance to reactive ion etching with O₂.

CONSTITUTION: This radiation sensitive resin compsn. is a mixture of 0.5g polysiloxane having 5,600wt. average mol.wt. and 1.5 specific dispersion with 50 mg triphenylsulfonium trifluoromethanesulfonate and 4ml 2-ethyl methoxyacetate as a solvent. The polysiloxane is a random copolymer contg. monomeric units represented by formula I and monomeric units represented by formula II and having a trimethylsilyl group at a terminal and 3:1 copolymn. ratio between p-hydroxy-m-allylphenetyl and t-butoxyl. In the formula II, R is an acid decomposable protective group having C forming an Si-O-C bond to Si in the skeleton of polysiloxane.

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